

Description

Yantel's high frequency surface mount highpass filters utilize Yantel's high dielectric ceramic materials which provide small size and minimal performance variation over temperature. The catalog HPF's are offered in a variety of frequency bands, which offers a drop in solution for high frequency attenuation.

Features

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

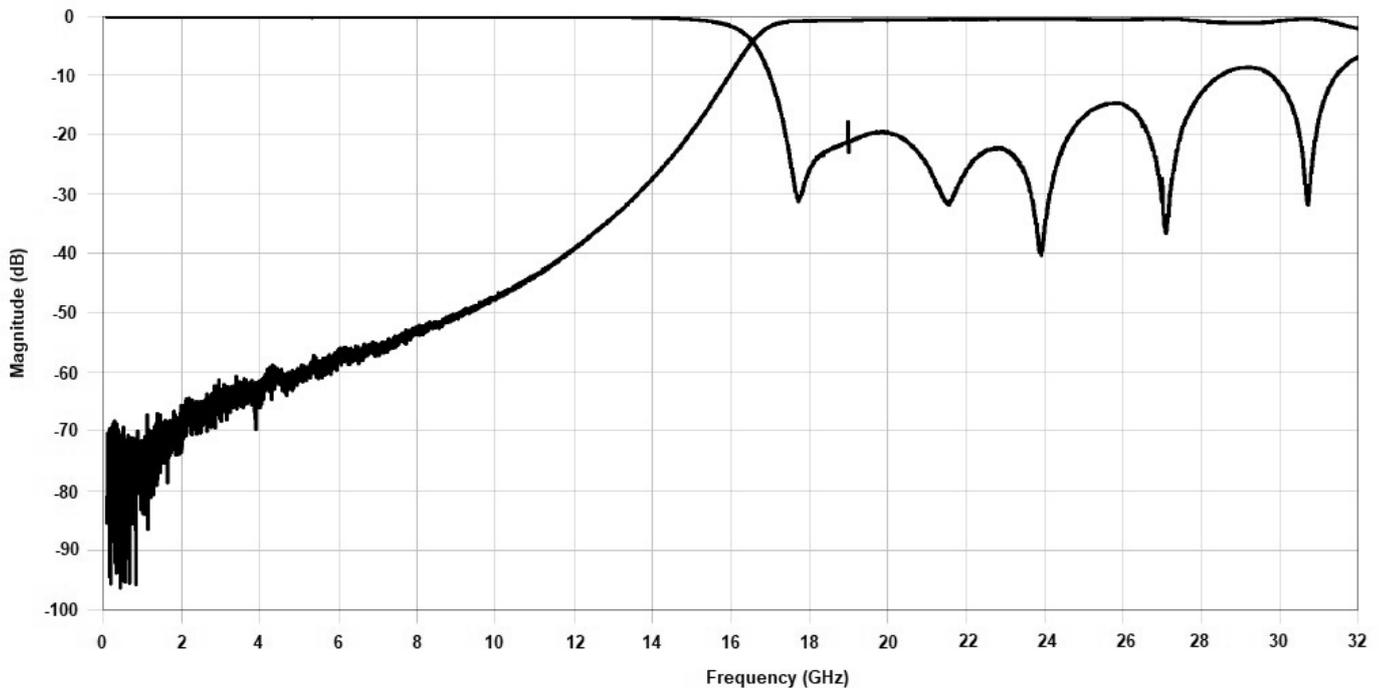
Specifications*

Parameter	Frequency Range (GHz)	Min	Typ.	Max
Insertion Loss (dB)	17.5 - 27.0		1.0	1.5
Return Loss (dB)		12.0	15.0	
Low Side Rejection (dB)	DC - 13.0	30.0	35.0	
CW Input Power** (W)				15.0
$\theta_{jc} \left(\frac{^{\circ}\text{C}}{\text{W}} \right)$	5.0			
Size (L x W x H)	11.43 x 4.45 x 2.50 mm			

*Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary ± 0.5 dB over temperature.

**Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat sink. Max power is based on 125°C base temperature.

Typical Measured Performance



*Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.0Ohm CPW ground traces going into the ports at room temperature.

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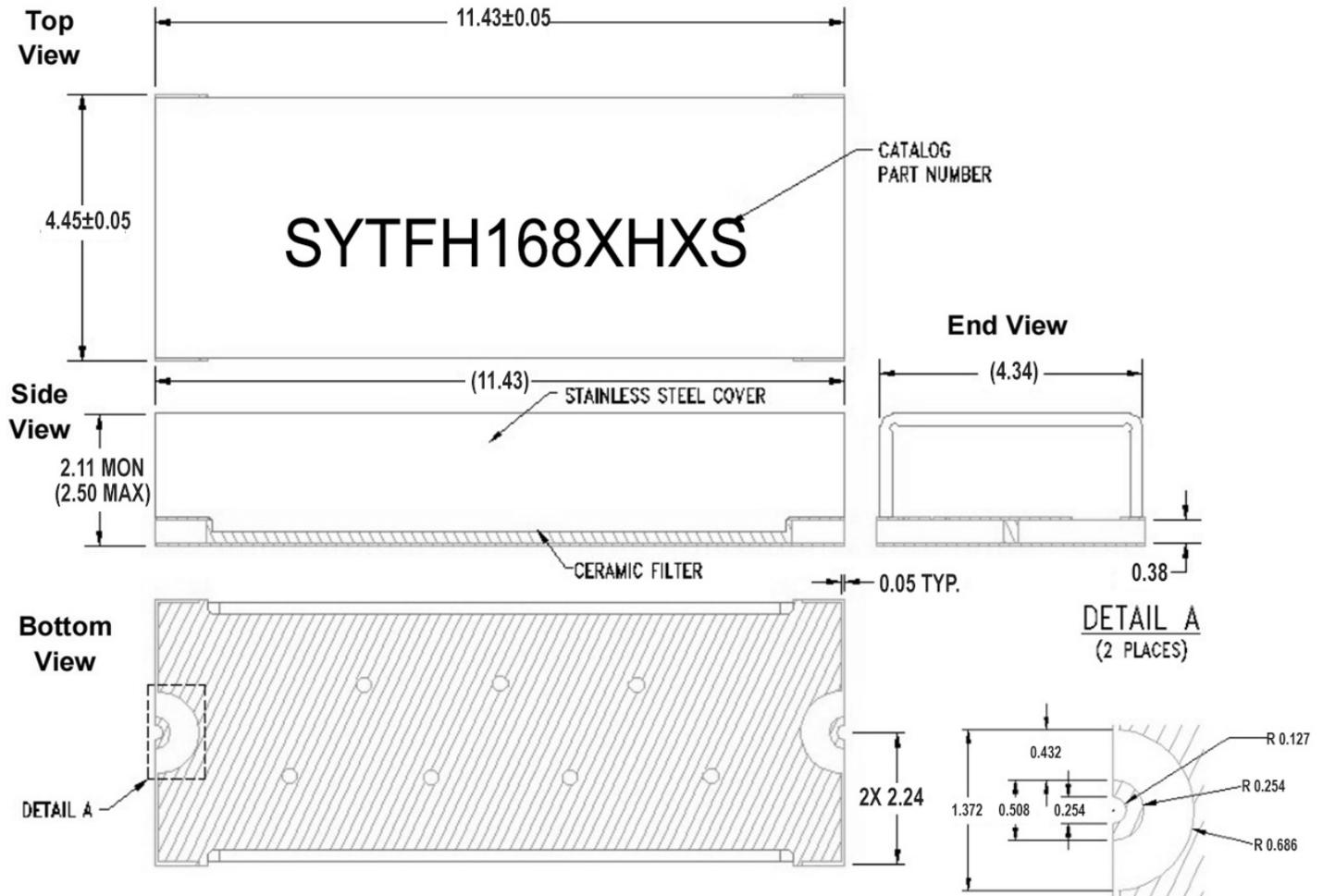
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For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com

Physical Dimensions

Units = mm

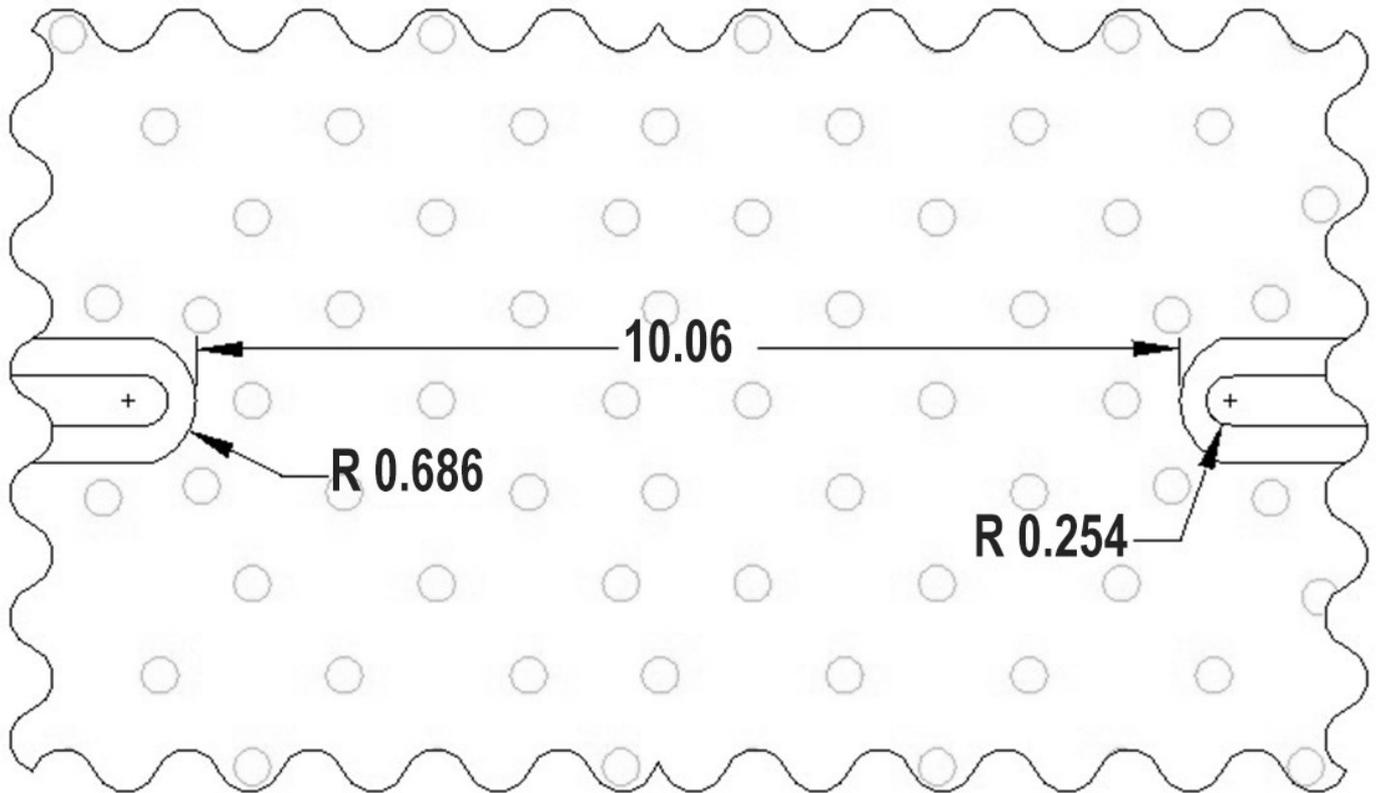


Notes :

1. Termination Finish:
 ENIG: 76-152 μm Au over 1270 μm Ni
2. Maximum Assembly Process Temperature: 250°C
3. Dimension tolerance: ±0.05

Recommended PCB Layout

Unit = mm



Note:

- 50Ω trace dimensions are application specific.
- Ensure adequate grounding beneath the part.